

## MiniSKiiP<sup>®</sup> 3

### Sixpack

### SKiiP 39AC12T7V1

#### Features\*

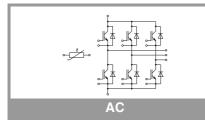
- 1200V Generation 7 IGBTs (T7)
- Robust and soft switching freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognized: File no. E63532

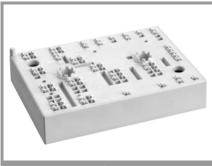
#### Remarks

- Max. case temperature limited to TC=TS=125 °C
- Product reliability results valid for Tj≤150 °C; Tj,op >150°C during overload (Details see AN19-002)
- MiniSKiiP "Technical Explanations" and "Mounting Instructions" are part of the data sheet. Please refer to both documents for further information.
- For storage and case temperature with TIM see document "Technical Explanations Thermal Interface Materials"

	e Maximum Rating			1		
Symbol	Conditions		Values	Unit		
Inverter -	IGBT					
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		1200	V		
lc	λ <sub>paste</sub> =0.8 W/(mK)	T <sub>s</sub> = 70 °C	139	А		
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 100 °C	112	A		
l <sub>c</sub>	λ <sub>paste</sub> =2.5 W/(mK)	T <sub>s</sub> = 70 °C	163	А		
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 100 °C	131	A		
I <sub>Cnom</sub>			150	Α		
I <sub>CRM</sub>			300	А		
V <sub>GES</sub>			-20 20	V		
t <sub>psc</sub>	$V_{CC} = 800 V$ $V_{GE} \le 15 V$ $V_{CES} \le 1200 V$	T <sub>j</sub> = 175 °C	7	μs		
Tj			-40 175	°C		
Inverse -	Diode	•		1		
V <sub>RRM</sub>	T <sub>j</sub> = 25 °C		1200	V		
IF	λ <sub>paste</sub> =0.8 W/(mK)	T <sub>s</sub> = 70 °C	103	А		
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 100 °C	82	A		
IF	λ <sub>paste</sub> =2.5 W/(mK)	T <sub>s</sub> = 70 °C	128	А		
	T <sub>j</sub> = 175 °C	T <sub>s</sub> = 100 °C	102	Α		
I <sub>FRM</sub>		•	300	A		
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms, sin 180°	°, T <sub>j</sub> = 150 °C	900	А		
Tj			-40 175	°C		
Module	•	•				
I <sub>t(RMS)</sub>	T <sub>terminal</sub> = 80 °C, 20	A per spring	160	А		
T <sub>stg</sub>	module without TIN	Λ	-40 125	°C		
V <sub>isol</sub>	AC sinus 50 Hz, t =	1 min	2500 V			

Symbol	Conditions		min.	typ.	max.	Unit
Inverter -	IGBT		•			
V <sub>CE(sat)</sub>	I <sub>C</sub> = 150 A	T <sub>j</sub> = 25 °C		1.55	1.70	V
	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 150 °C		1.73	1.88	V
	chiplevel	T <sub>j</sub> = 175 °C		1.77	1.92	V
V <sub>CE0</sub>		T <sub>j</sub> = 25 °C		1.00	1.05	V
	chiplevel	T <sub>j</sub> = 150 °C		0.80	0.85	V
		T <sub>j</sub> = 175 °C		0.75	0.80	V
r <sub>CE</sub>		T <sub>j</sub> = 25 °C		3.7	4.3	mΩ
	V <sub>GE</sub> = 15 V _ chiplevel	T <sub>j</sub> = 150 °C		6.2	6.9	mΩ
		T <sub>j</sub> = 175 °C		6.8	7.5	mΩ
V <sub>GE(th)</sub>	$V_{GE} = V_{CE}, I_C = 3.4$	mA	5.15	5.8	6.45	V
I <sub>CES</sub>	$V_{GE} = 0 V, V_{CE} = 12$	200 V, T <sub>j</sub> = 25 °C			1.5	mA
Cies	V 05.V	f = 1 MHz		30.20		nF
Coes	V <sub>CE</sub> = 25 V V <sub>GE</sub> = 0 V	f = 1 MHz		0.39		nF
C <sub>res</sub>		f = 1 MHz		1.08		nF
Q <sub>G</sub>	V <sub>GE</sub> = - 8V + 15	V		2100		nC
R <sub>Gint</sub>	T <sub>i</sub> = 25 °C			1.0		Ω





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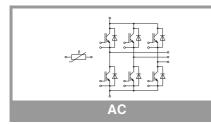
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Symbol	Conditions		min.	typ.	max.	Unit		
Inverter -	IGBT							
t <sub>d(on)</sub>		T <sub>j</sub> = 25 °C		173		ns		
		T <sub>j</sub> = 150 °C		181		ns		
		T <sub>j</sub> = 175 °C		179		ns		
t <sub>r</sub>		T <sub>j</sub> = 25 °C		32				
	V <sub>CC</sub> = 600 V	T <sub>j</sub> = 150 °C		37		ns		
	$I_{\rm C} = 150 \rm{A}$	T <sub>j</sub> = 175 °C		39		ns		
Eon	$R_{G \text{ on}} = 1.1 \Omega$	T <sub>j</sub> = 25 °C		6.9		mJ		
	$R_{G off} = 1.1 \Omega$	T <sub>j</sub> = 150 °C		12		mJ		
	V <sub>GE</sub> = +15/-15 V	T <sub>j</sub> = 175 °C 13				mJ		
t <sub>d(off)</sub>		T <sub>j</sub> = 25 °C 347				ns		
	di/dt <sub>on</sub> = 3970 A/µs di/dt <sub>off</sub> = 1530 A/µs dv/dt = 3730 V/µs	T <sub>j</sub> = 150 °C		437		ns		
		T <sub>j</sub> = 175 °C	462			ns		
t <sub>f</sub>		T <sub>j</sub> = 25 °C		67				
		T <sub>j</sub> = 150 °C 103				ns		
		T <sub>j</sub> = 175 °C	130			ns		
E <sub>off</sub>		T <sub>j</sub> = 25 °C		10		mJ		
		T <sub>j</sub> = 150 °C		17				
	1	T <sub>j</sub> = 175 °C		18		mJ		
R <sub>th(j-s)</sub>	per IGBT, λ <sub>paste</sub> =0.8	3 W/(mK)		0.41				
R <sub>th(j-s)</sub>	per IGBT, λ <sub>paste</sub> =2.5	5 W/(mK)		0.32		K/W		

### Characteristics Symbol Conditions Inverse - Diode

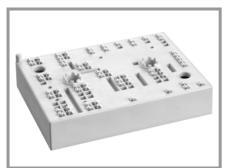
Inverse -	Diode				
$V_F = V_{EC}$	I <sub>F</sub> = 150 A	T <sub>j</sub> = 25 °C	2.1	4 2.46	V
	$V_{GE} = 0 V$	T <sub>j</sub> = 150 °C	2.0	07 2.38	V
	chiplevel	T <sub>j</sub> = 175 °C	1.9	93 2.24	V
V <sub>F0</sub>		T <sub>j</sub> = 25 °C	1.3	30 1.50	V
	chiplevel	T <sub>j</sub> = 150 °C	0.9	90 1.10	V
	_	T <sub>j</sub> = 175 °C	0.8	.98 0.98	V
r <sub>F</sub>		T <sub>j</sub> = 25 °C	5.	6 6.4	mΩ
	chiplevel	T <sub>j</sub> = 150 °C	7.	8 8.5	mΩ
		T <sub>j</sub> = 175 °C	7.	4 8.4	mΩ
I <sub>RRM</sub>		T <sub>j</sub> = 25 °C	10	7	А
		T <sub>j</sub> = 150 °C	14	5	А
	I <sub>F</sub> = 150 A	T <sub>j</sub> = 175 °C	17	5	А
Q <sub>rr</sub>	V <sub>GE</sub> = +15/-15 V V <sub>CC</sub> = 600 V	T <sub>j</sub> = 25 °C	7.	4	μC
		T <sub>j</sub> = 150 °C	24	4	μC
	@ T <sub>i</sub> = 150 °C:	T <sub>j</sub> = 175 °C	24	.5	μC
E <sub>rr</sub>	$di/dt_{off} = 3910 \text{ A/}\mu\text{s}$	•	2.	6	mJ
		T <sub>j</sub> = 150 °C	8.	6	mJ
		T <sub>j</sub> = 175 °C	1	1	mJ
R <sub>th(j-s)</sub>	per Diode, $\lambda_{\text{paste}}=0$ .	8 W/(mK)	0.5	55	K/W
R <sub>th(j-s)</sub>	per Diode, $\lambda_{\text{paste}}=2$ .	5 W/(mK)	0.	4	K/W
Module					
L <sub>CE</sub>			-		nH
Ms	to heat sink		2	2.5	Nm
w			82	2	g

min.

typ.

max.

Unit



### Characteristics

Characte	ristics				
Symbol	Conditions	min.	typ.	max.	Unit
Temperat	ure Sensor				
R <sub>100</sub>	T <sub>r</sub> =100°C (R <sub>25</sub> =1000Ω)		1670 ± 3%		Ω
R <sub>(T)</sub>	$\begin{split} &R_{(T)}{=}1000\Omega[1{+}A(T{-}25^\circC){+}B(T{-}25^\circC)^2]\\ ,A=7.635^*10^{-3\circ}C^{-1},\\ &B=1.731^*10^{-5\circ}C^{-2} \end{split}$				

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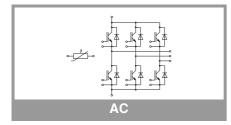
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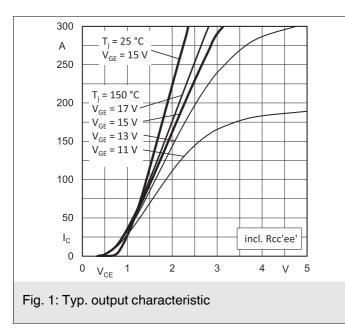
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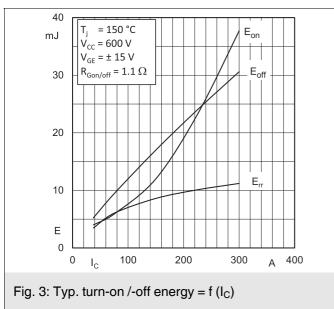
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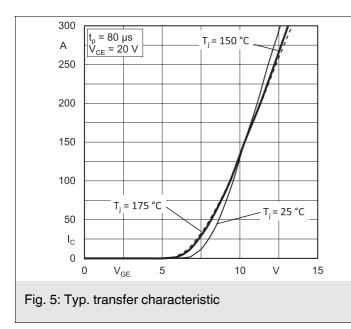
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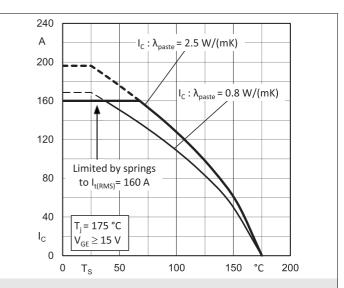
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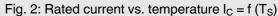


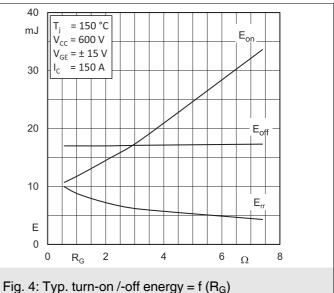


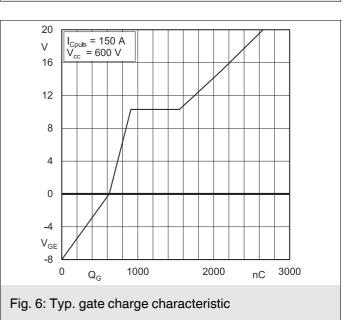


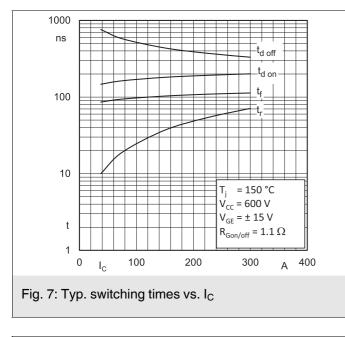


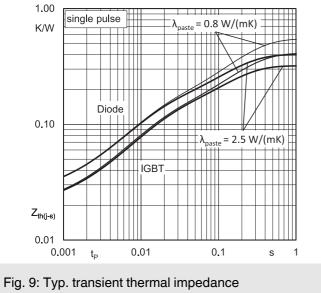


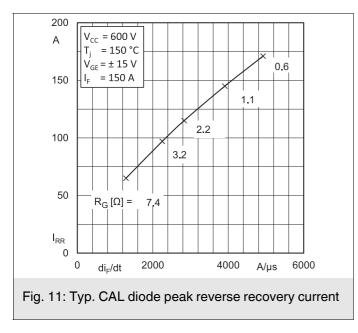


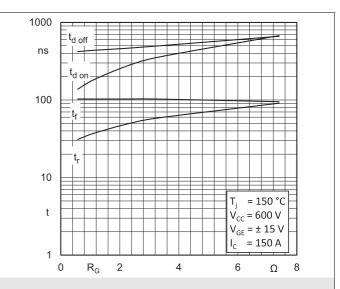


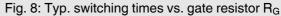


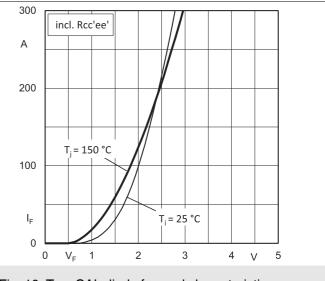


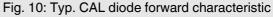


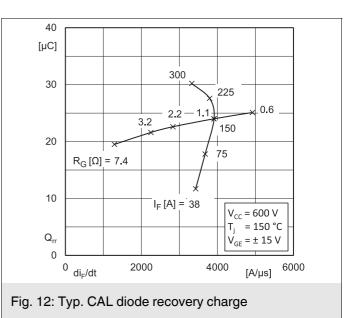






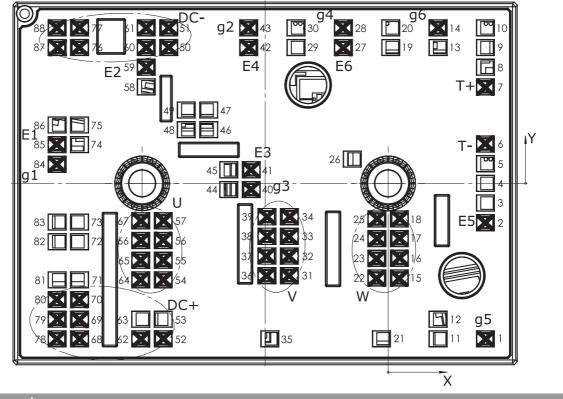




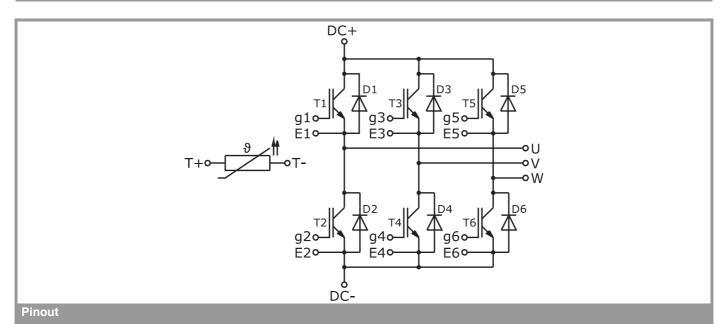


Pin out											
Pin	X	Y	Function	Pin	X	Ŷ	Function	Pin	X	Ŷ	Function
1	15,83	-25,30	g5	31	-16,05	-15,02	V	61	-39,33	25,30	DC-
2	15,83	-6,40	E5	32	-16,05	-11,82	V	62	-40,23	-25,30	DC+
З	15,83	-3,20		33	-16,05	<del>-</del> 8,62	V	63	-40,23	<del>-</del> 22,10	
4	15,83	0		34	-16,05	-5,42	V	64	-40,23	-15,70	U
5	15,83	3,20		35	<del>-</del> 19,23	<del>-</del> 25,30		65	-40,23	-12,50	U
6	15,83	6,40	T-	36	-19,70	-15,02	V	66	-40,23		U
7	15,83	15,70	T+	37	-19,70	-11,82	V	67	-40,23		U
8	15,83	18,90		38	-19,70	-8,62	V	68		-25,30	
9	15,83	22,10		39	-19,70	<del>-</del> 5,42	V	69		<del>-</del> 22,10	DC+
10	15,83	25,30		40	-22,26			70	-50,18	-18,90	DC+
11	8,13	-25,30		41	-22,26			71		-15,70	
12	8,13	-22,10		42	-22,68	22,10		72	-50,18	-9,50	
13	8,13	22,10		43	-22,68	25,30	g2	73	-50,18		
14	8,13	25,30	g6	44	-25,91	-1,00		74	-50,18		
15	1,83	-15,39	W	45	-25,91	2,20		75	-50,18		
16	1,83	-12,19	W	46	-29,18	8,74		76	-50,18		
17	1,83	-8,99	W	47	-29,18	11,94		77	-50,18	25,30	DC-
18	1,83	-5,79	W	48	-32,83	8,74		78	-53,83	-25,30	DC+
19	0,43	22,10		49	-32,83	11,94		79	-53,83	-22,10	DC+
20	0,43	25,30		50	-35,68	22,10		80	-53,83		DC+
21	-1,08	-25,30		51	-35,68	25,30	DC-	81	-53,83	-15,70	
22	-1,83	-15,39	W	52	-36,58			82	-53,83		
23	-1,83	-12,19	W	53	-36,58			83	-53,83	-6,30	
24	-1,83	-8,99	W	54	-36,58	-15,70	U	84	-53,83		g1
25	-1,83	<del>-</del> 5,79	W	55	-36,58	<del>-</del> 12,50	U	85	-53,83	6,30	E1
26	-5,83	3,95		56	-36,58		U	86	-53,83		
27	-7,28	22,10	E6	57	-36,58			87	-53,83		
28	-7,28	25,30	g4	58	-39,33	15,70		88	-53,83	25,30	DC-
29	-14,98	22,10		59	-39,33	18,90	E2				
30	-14,98	25,30		60	-39,33	22,10	DC-				

all values in mm



**Pinout and Dimensions** 



This is an electrostatic discharge sensitive device (ESDS) due to international standard IEC 61340.

#### **\*IMPORTANT INFORMATION AND WARNINGS**

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